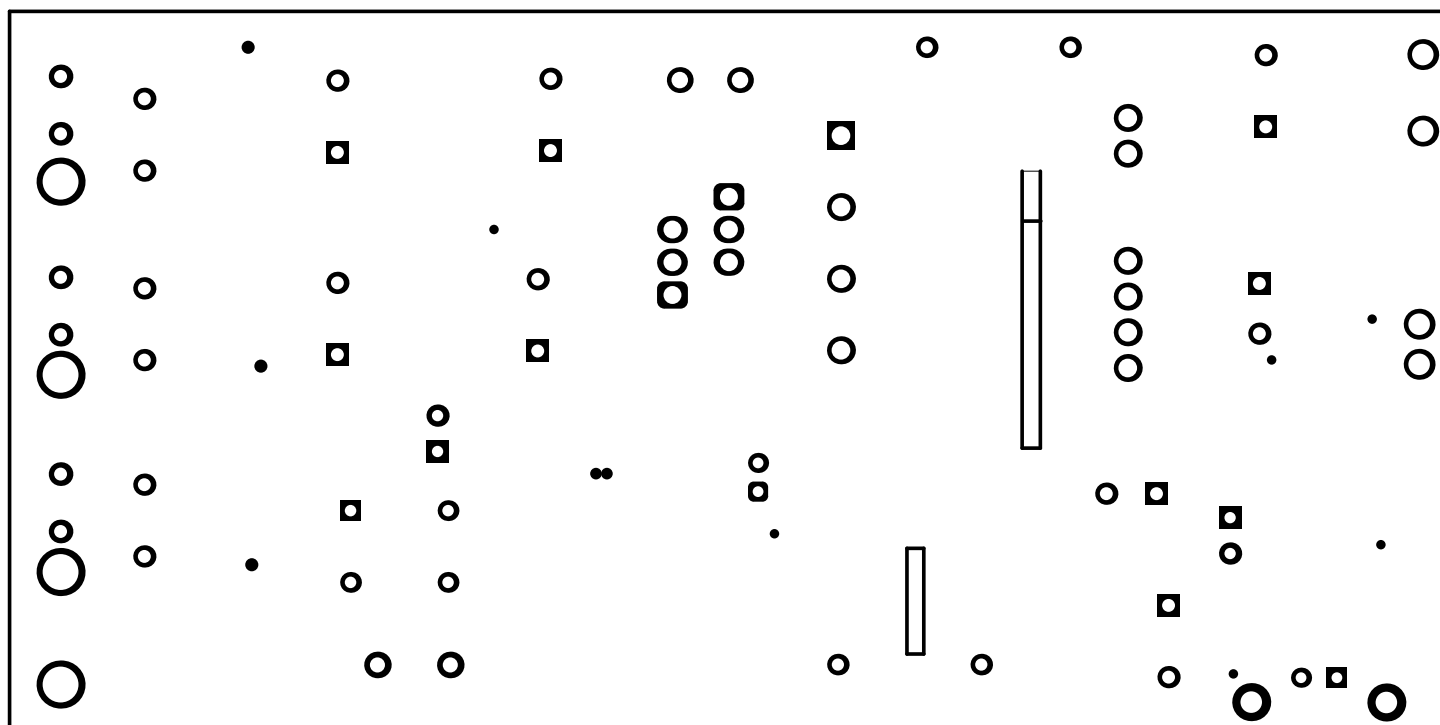
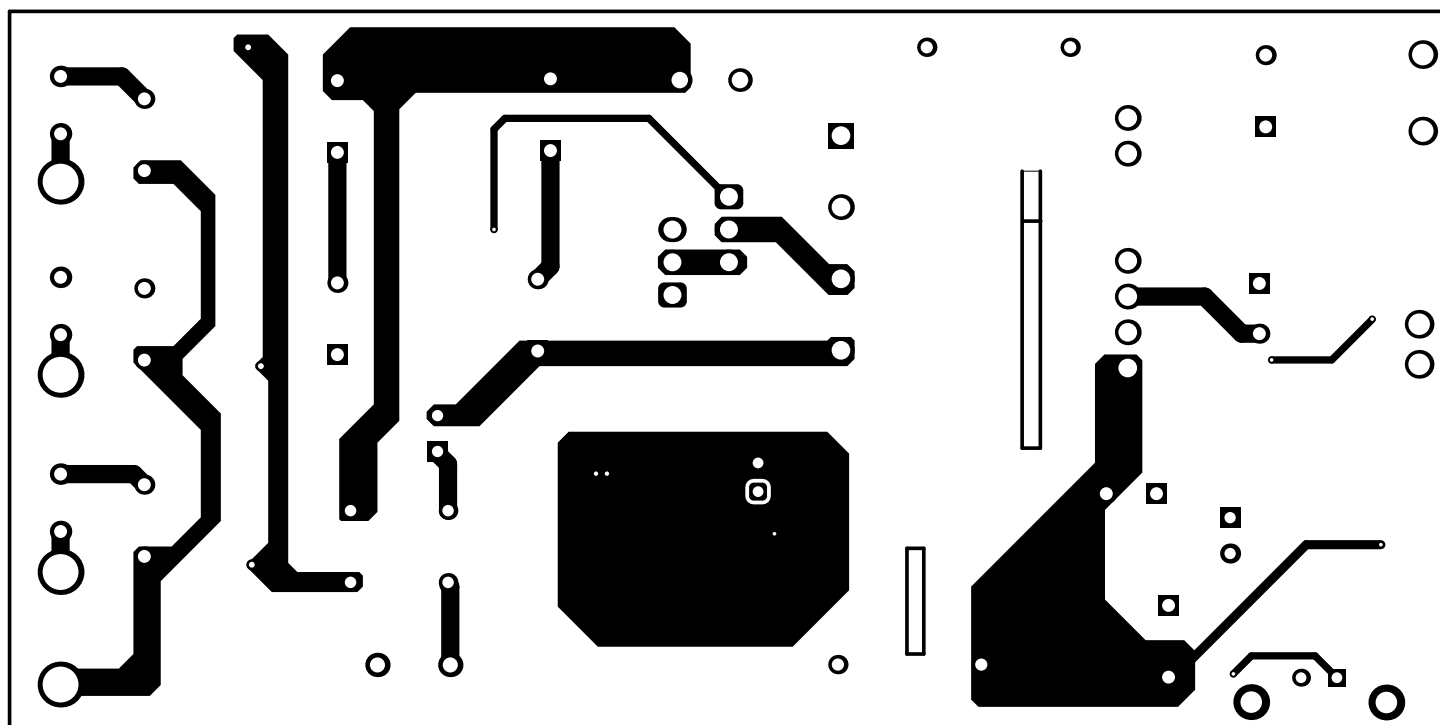


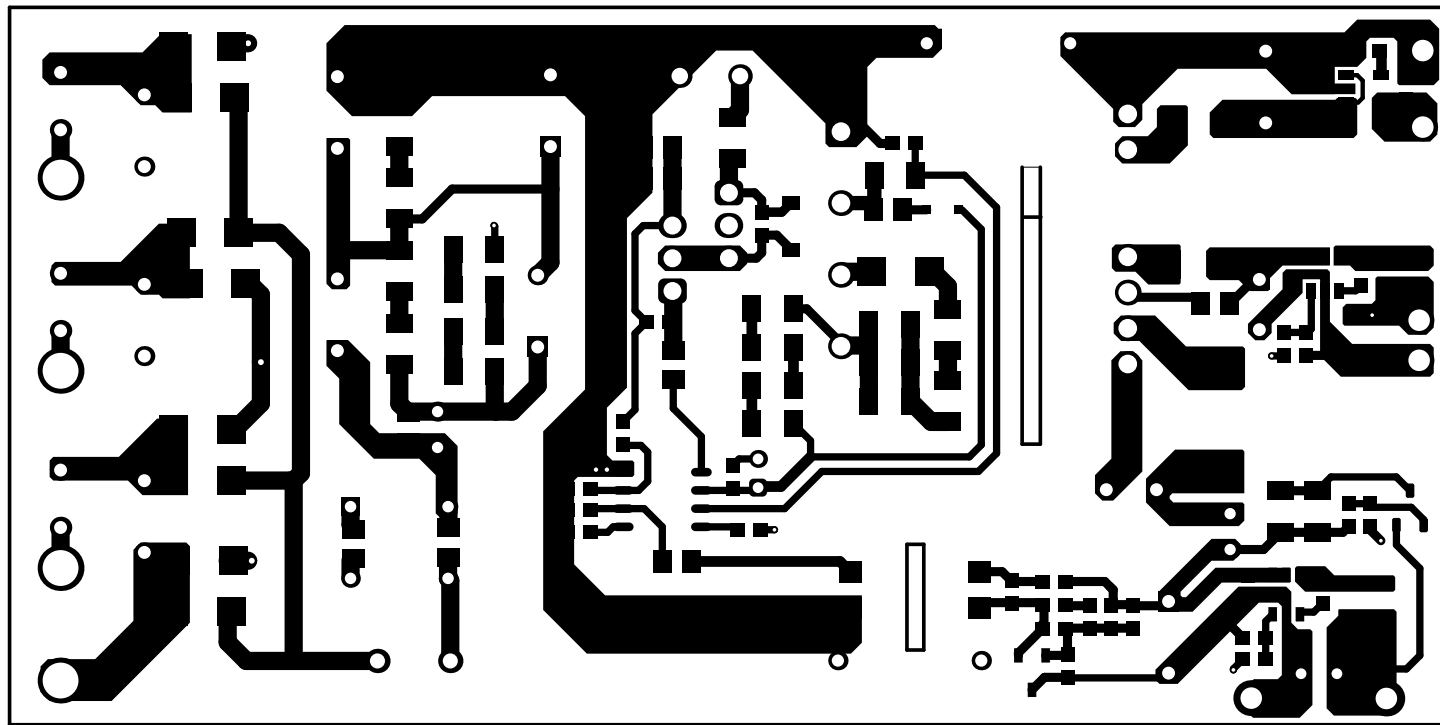
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40347	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: PMP40347		
PLOT NAME = Top Overlay	GENERATED : 3/25/2018 10:36:41 PM	TEXAS INSTRUMENTS	



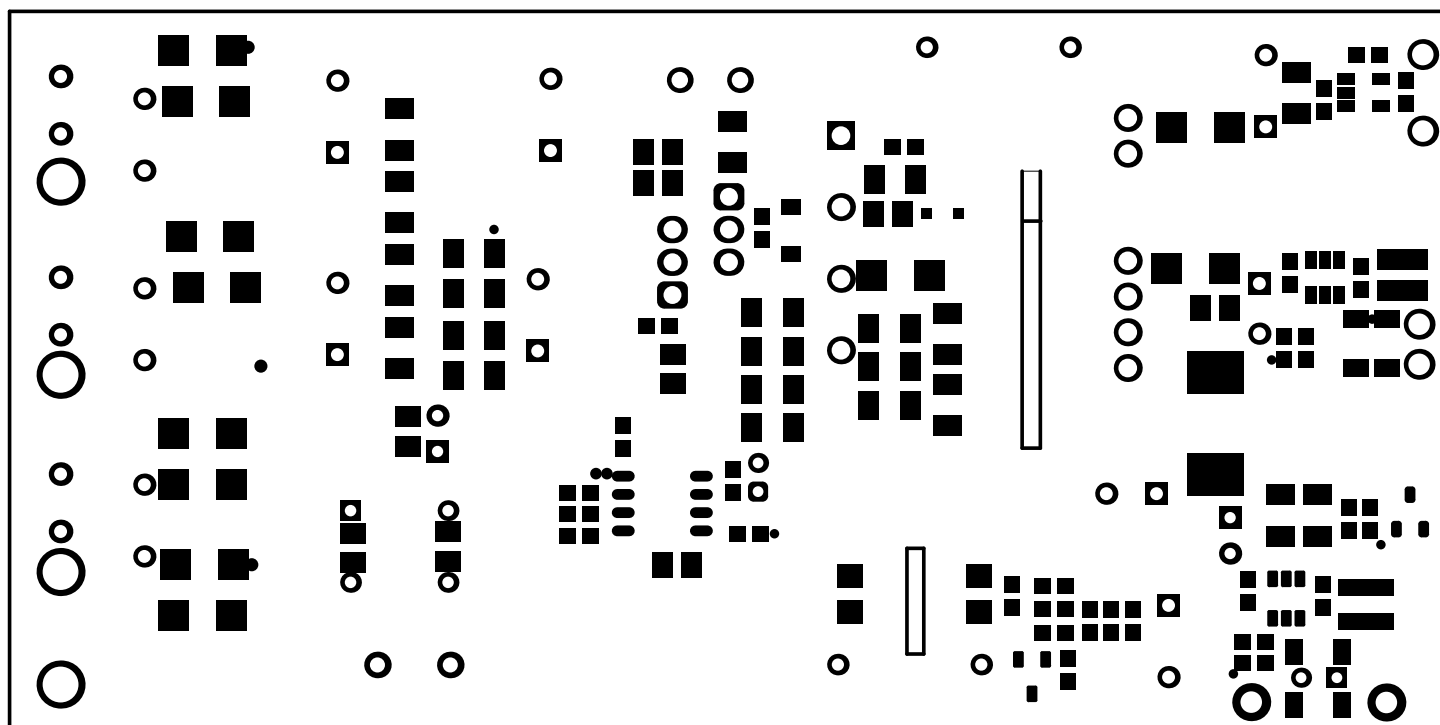
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40347	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: PMP40347		
PLOT NAME = Top Solder Mask	GENERATED : 3/25/2018 10:36:41 PM	TEXAS INSTRUMENTS	



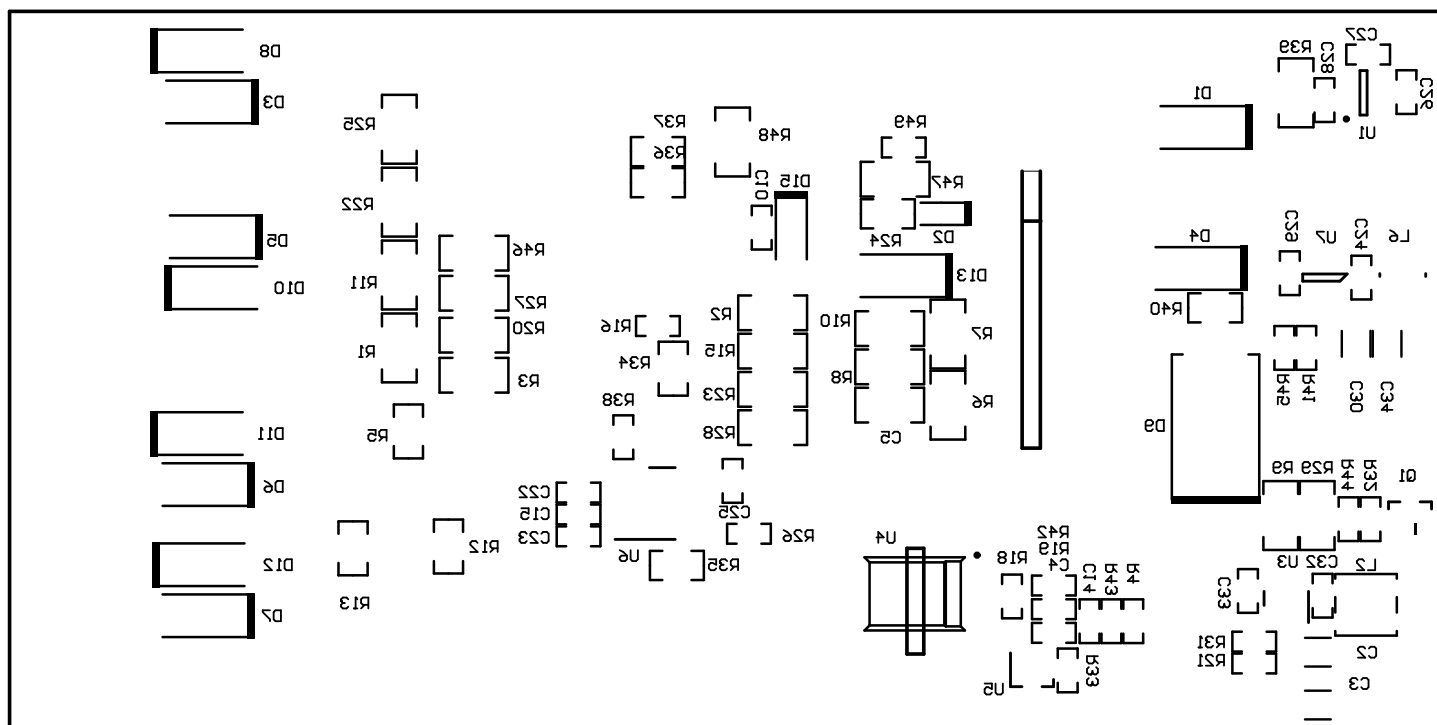
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40347	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: PMP40347		
PLOT NAME = Top Layer	GENERATED : 3/25/2018 10:36:41 PM	TEXAS INSTRUMENTS	



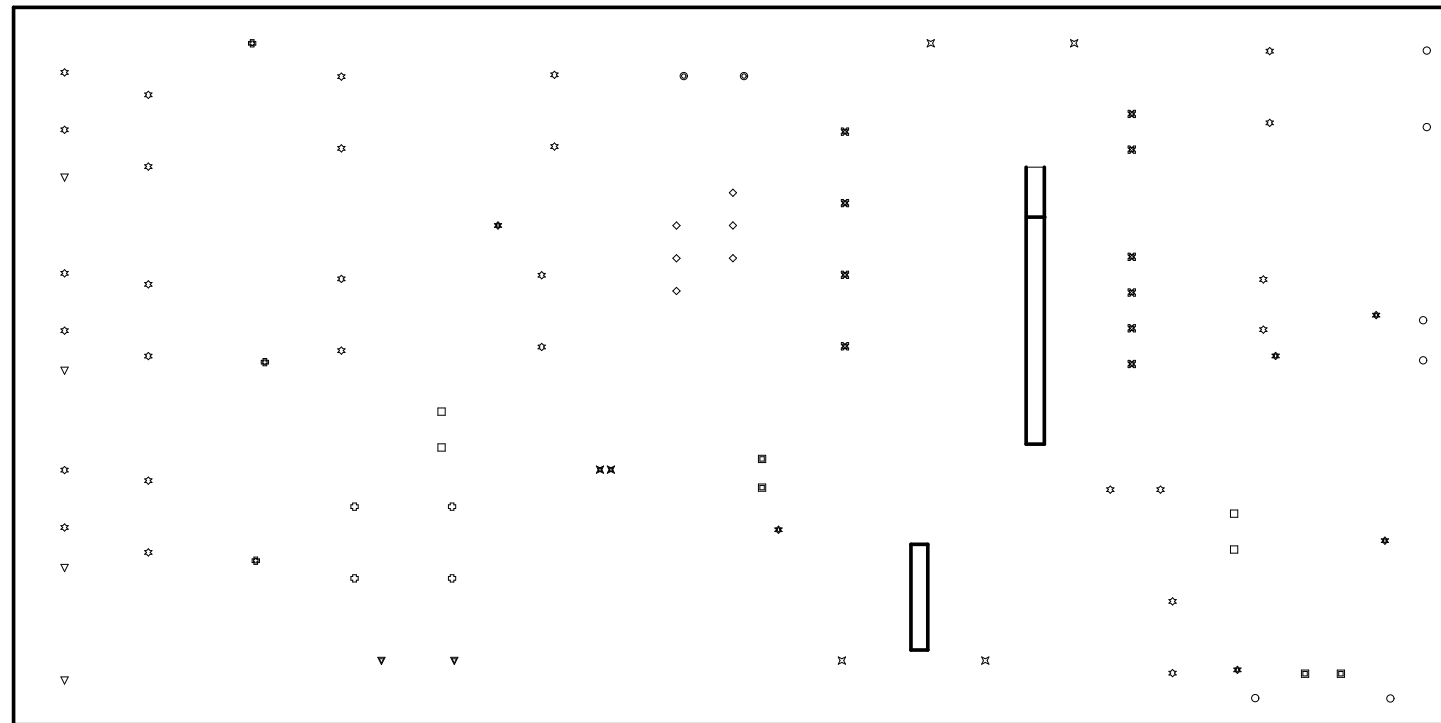
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40347	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: PMP40347		
PLOT NAME = Bottom Layer	GENERATED : 3/25/2018 10:36:41 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40347	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: PMP40347		
PLOT NAME = Bottom Solder Mask	GENERATED : 3/25/2018 10:36:42 PM	TEXAS INSTRUMENTS	

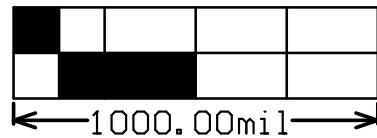
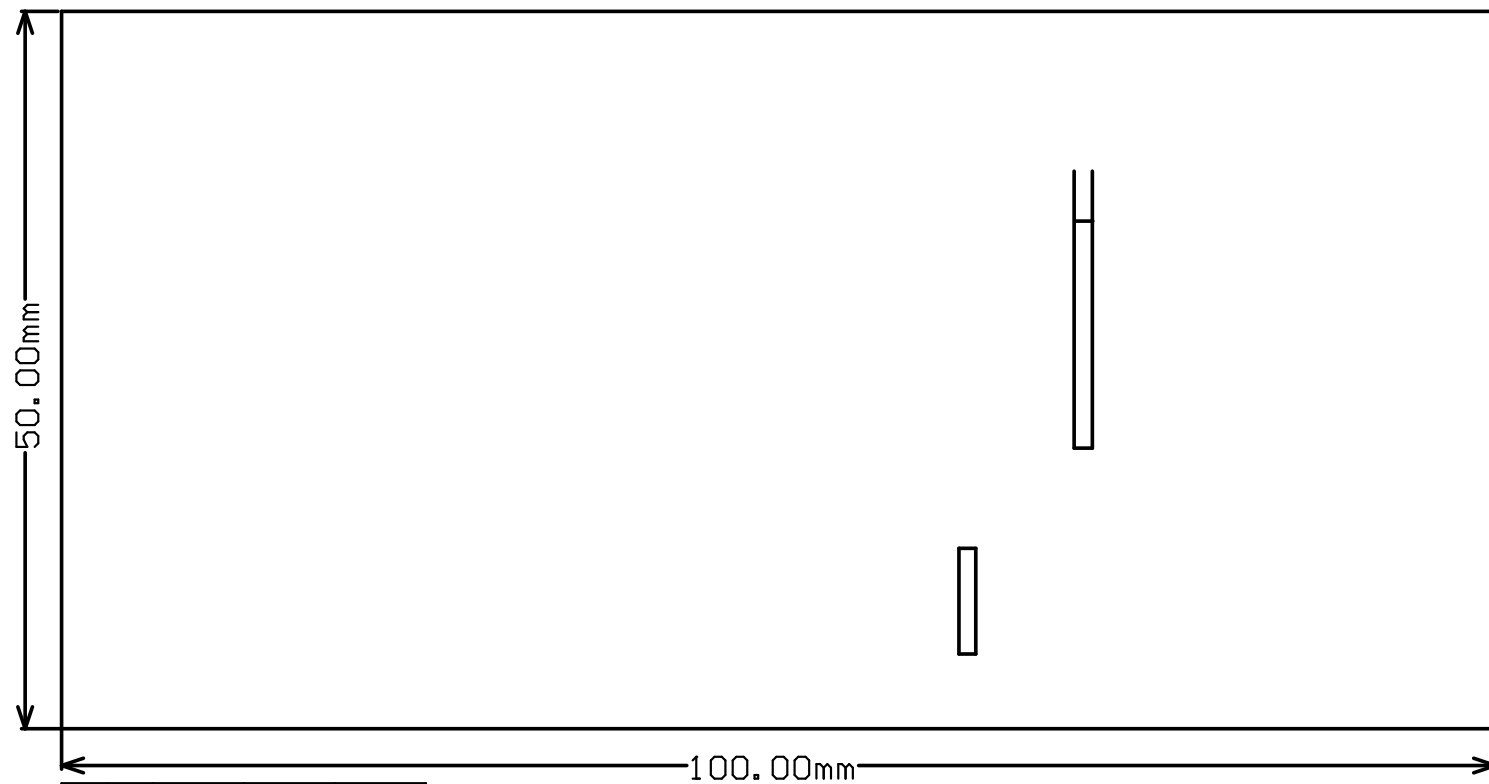


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40347	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: PMP40347		
PLOT NAME = Bottom Overlay	GENERATED : 3/25/2018 10:36:42 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
☆	6	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
✕	2	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	3	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
◻	4	29.53mil (0.750mm)	PTH	Round	Top Layer - Bottom Layer	
□	4	31.00mil (0.787mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	4	31.50mil (0.800mm)	PTH	Round	Top Layer - Bottom Layer	
✕	4	33.47mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
☆	28	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
▽	2	41.34mil (1.050mm)	PTH	Round	Top Layer - Bottom Layer	
⊙	2	45.28mil (1.150mm)	PTH	Round	Top Layer - Bottom Layer	
◇	6	49.21mil (1.250mm)	PTH	Round	Top Layer - Bottom Layer	
✕	10	51.18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer	
○	6	59.06mil (1.500mm)	PTH	Round	Top Layer - Bottom Layer	
▽	4	98.43mil (2.500mm)	PTH	Round	Top Layer - Bottom Layer	
	85 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40347	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: PMP40347		
PLOT NAME = Drill Drawing	GENERATED : 3/25/2018 10:36:42 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40347	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: PMP40347		
PLOT NAME = Board Dimensions	GENERATED : 3/25/2018 10:36:43 PM		TEXAS INSTRUMENTS

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